



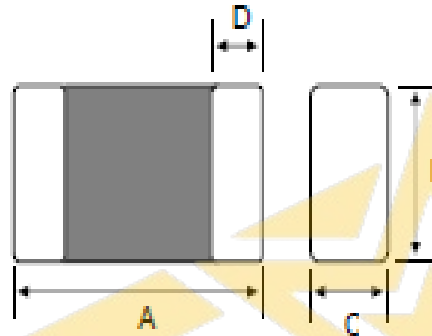
Physical Dimensions : mm (inch)

A =  $2.0 \pm 0.2$  (0.079 $\pm$ 0.008)

B =  $1.2 \pm 0.2$  (0.047 $\pm$ 0.008)

C =  $0.9 \pm 0.2$  (0.035 $\pm$ 0.008)

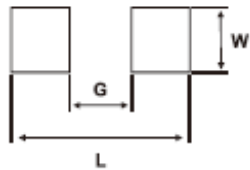
D =  $0.5 \pm 0.3$  (0.020 $\pm$ 0.012)



General Information :

1. Termination Finish is 100% Tin.
2. Components Should be Adequately Preheated Before Soldering.
3. Operating Temperature: -55°C to +125°C
4. Storage Temperature (on Tape & Reel): 40°C MAX. , 70% RH

Land Patterns for Reflow Soldering



L	W	G
3.20(0.126)	1.50(0.059)	0.60(0.024)

Packing Method:

One reel = 4,000 pcs

One Box = 200,000 pcs

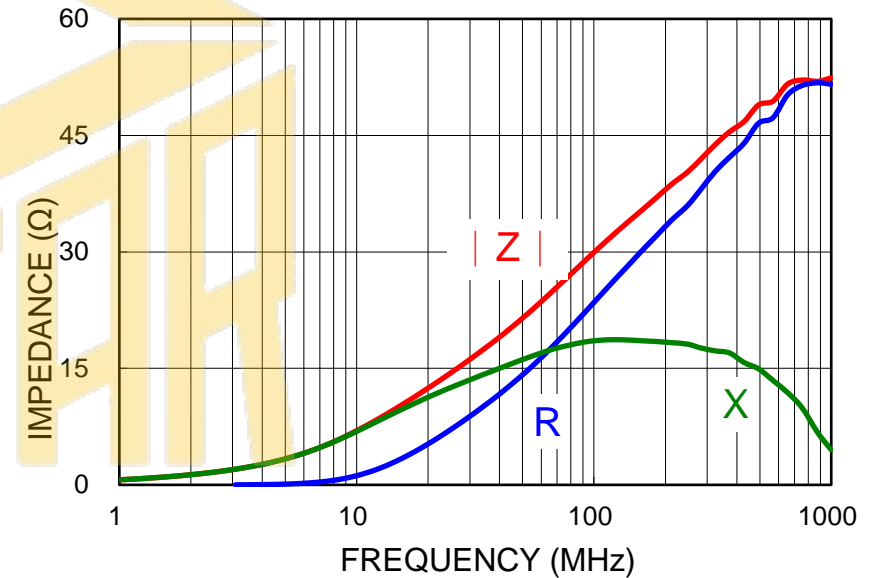
One Box = 10.3 KG

Electrical Characteristics :

	Value	Unit	Tolerance	Test Condition
Impedance	30	$\Omega$	$\pm 25\%$	100MHz / 100mV
DCR	0.15	$\Omega$	Max.	
IDC	400	mA	Max.	

Typical Impedance Characteristics : HP 4291B

TB201209U300



Multilayer Ferrite Chip Beads

P/N TB 201209 U300

Version N000



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www.tecstar.com.tw

N000	Initial		
VER.	DESCRIPTION	DATE	BY